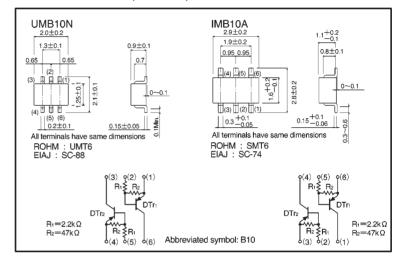
General purpose (dual digital transistors) UMB10N/IMB10A

Features

- Two DTA123J chips in a UMT or SMT package.
- Mounting possible with UMT3 or SMT3 automatic mounting machines.
- Transistor elements are independent, eliminating interference.
- Mounting cost and area can be cut in half.

StructureEpitaxial planar typePNP silicon transistor(Built-in resistor type)

External dimensions (Units: mm)



The following characteristics apply to both DTr₁ and DTr₂.

■Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	Limits	Unit	
Supply voltage		Vcc	—50	V	
Input voltage		Vin	-12	V	
		VIN	5		
Output current		lo	-100	mA	
		IC(Max.)	-100	mA	
Power dissipation	UMB10N	Pd	150 (TOTAL)	*1 mW	
	IMB10A	Pu	300 (TOTAL)	*2	
Junction temperature		Tj	150 °C		
Storage temperature		Tstg	-55~+150	Ĉ	

^{*1 120}mW per element must not be exceeded.

^{*2 200}mW per element must not be exceeded.

●Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Input voltage	VI (off)	_	_	-0.3	٧	Vcc=-5V, Io=-100 μ A	
input voltage	VI (on)	-1.1	_	_		Vo=-0.3V, Io=-5mA	
Output voltage	V _O (on)	_	一0.1	-0.3	V	lo/li=-5mA/-0.25mA	
Input current	lı	_	_	-3.6	mA	V₁=-5V	
Output current	IO(off)	_	_	-0.5	μΑ	Vcc=-50V, Vi=0V	
DC current gain	Gı	80	_	_	_	Vo=-5V, Io=-10mA	
Transition frequency	fτ	_	250	_	MHz	Vc=-10mA, l==5mA, f=100MHz *	
Input resistance	R ₁	1.54	2.2	2.86	kΩ	_	
Resistance ratio	R2/R1	17	21	26	_	_	

^{*} Transition frequency of the device

Packaging specifications

	Packaging type	Taping	
	Code	TN	T110
Part No.	Basic ordering unit (pieces)	3000	3000
UMB10N	_	0	_
IMB10A		_	0

Electrical characteristic curves

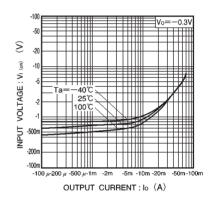


Fig.1 Input voltage vs. output current (ON characteristics)

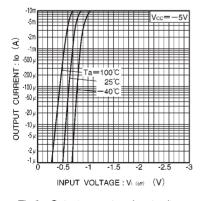


Fig.2 Output current vs. input voltage (OFF characteristics)

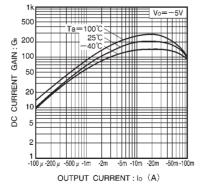


Fig.3 DC current gain vs. output current

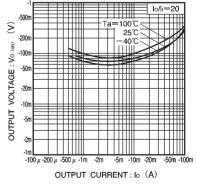


Fig.4 Output voltage vs. output current